ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES International and P	IPC, Bannockl	ourn, Illinois. A	Il rights reserved untions.	under both	This docum level parts, t	ent is a declara	ation of the encompass	substance ses all low	s within the er level ma	e manufactur terials for wl	er listed iter hich the ma	n. Note: nufactur	if the item is an as er has engineering	ssembly with low responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form T http://www.ipc.org/IPC-175x Distribution				*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mfg Information			
Supplier Information														
Company name* Co			Company unique ID			Unique ID Authority					Response Date*			
onsemi											2024-05-11			
Contact Name Title - Contact			ct	Pho			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product En			uct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Rep			- Representative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Pro			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Da	te Versio	n	Manufacturing Site		W	eight*	UOM	Unit Type
	DTC115	DTC115TET1G NPN Digital Tra		nsistor (BRT)		2024-05-11					2.5	51	mg	Each
Aanufacturing Proccess Inform	ation													
Terminal Plating / Grid Array M	Plating / Grid Array Material Terminal Base Al		Alloy	-STD-020 MSL Rating		Peak Process Body Temperature Max Time at Peak		ime at Peak	Temperature Number of Reflow Cycles					
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30		seconds	3		
omments														
vel 1 - maximum time at peak tempera	ture during so	Idering is 10-3	0 seconds											
or more information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless	otherwise noted).				-	_		-
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.06	mg	Supplier	Silicon (Si)	7440-21-3		0.06	mg
Lead Frame	0.75	mg	В	Nickel (Ni)	7440-02-0		0.2843	mg
			Supplier	Iron (Fe)	7439-89-6		0.393	mg
			Supplier	Copper (Cu)	7440-50-8		0.0727	mg
Mold Compound-Black	1.57	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.157	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0078	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.2277	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1.0205	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.157	mg
Plating	0.12	mg	Supplier	Tin (Sn)	7440-31-5		0.12	mg
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg